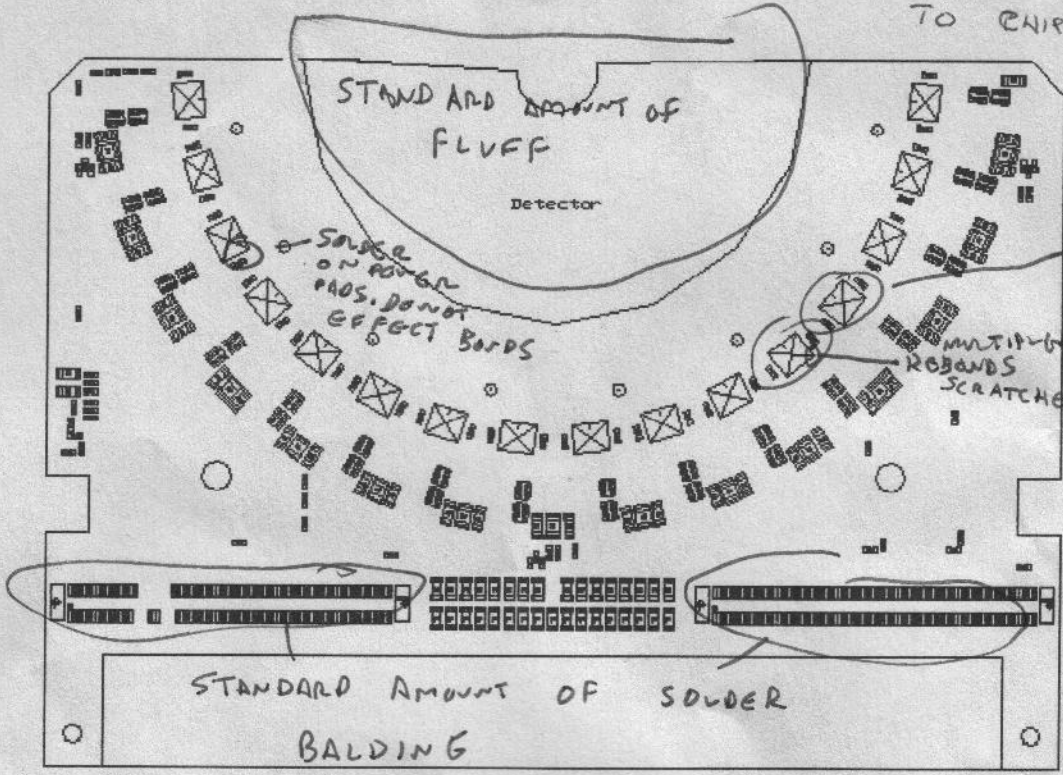


BOND REMOVED, CHIP
 REDUNDANT PAD 145 (DUPP)
~~REMOVED~~ WITH 2 WIRE BONDS
 TO CHIP PAD 169

R side



Phi side

